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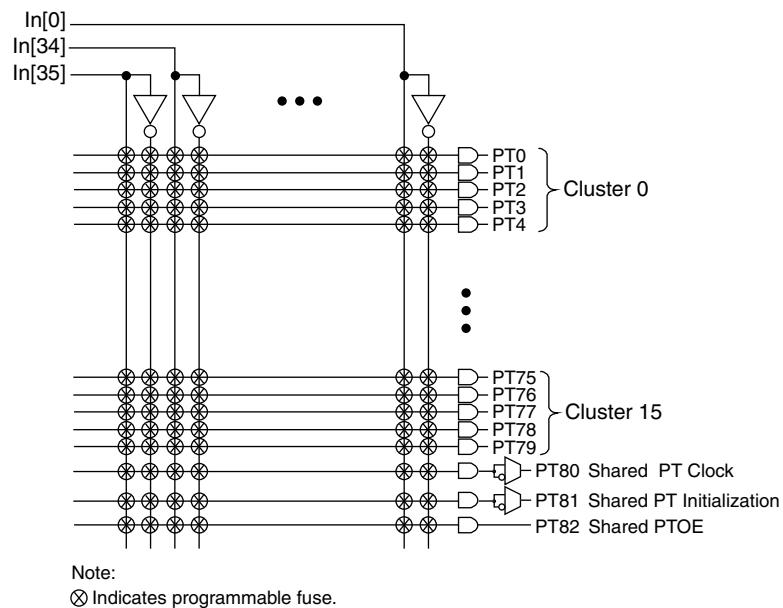
Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	2.3V ~ 2.7V
Number of Logic Elements/Blocks	24
Number of Macrocells	384
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4384b-5t176c

Figure 3. AND Array

Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

Figure 4. Macrocell Slice

Table 10. ORP Combinations for I/O Blocks with 12 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

ORP Bypass and Fast Output Multiplexers

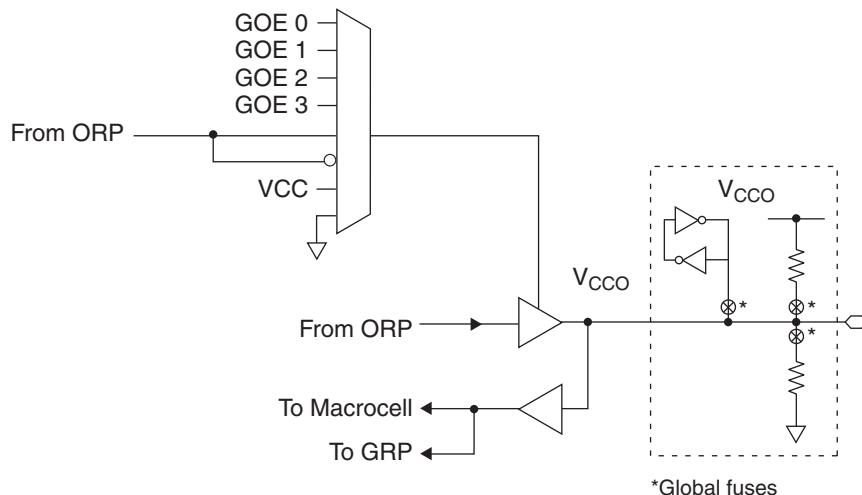
The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster t_{CO} .

Output Enable Routing Multiplexers

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

I/O Cell

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

Figure 8. I/O Cell

Each output supports a variety of output standards dependent on the V_{CCO} supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the V_{CCO} supplied to its I/O bank. The I/O standards supported are:

I/O Recommended Operating Conditions

Standard	V_{CCO} (V) ¹	
	Min.	Max.
LV TTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 ²	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for V_{CCO} are the average of the min. and max. values.

2. ispMACH 4000Z only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	μA
I_{IH}^1	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	μA
I_{IL}, I_{IH}^1	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$ $0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	10	μA
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$ $3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	μA
I_{PD}	I/O Weak Pull-down Resistor Current	$V_{IL} (\text{MAX}) \leq V_{IN} \leq V_{IH} (\text{MIN})$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (\text{MAX})$	30	—	—	μA
I_{BHHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	μA
V_{BHT}	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
C_1	I/O Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	8	—	pf
C_2	Clock Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	6	—	pf
C_3	Global Input Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$.

3. $T_A = 25^\circ C, f = 1.0MHz$

4. I_{IH} excursions of up to $1.5\mu A$ maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

ispMACH 4000Z External Switching Characteristics**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
t_{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
t_S	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
t_{ST}	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
t_{SIR}	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
t_{SIRZ}	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
t_H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t_{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
t_{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
t_R	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
t_{RW}	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
$t_{PTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
$t_{GPTOE/DIS}$	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
t_{CW}	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
t_{WIR}	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
f_{MAX}^4	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
f_{MAX} (Ext.)	clock frequency with external feedback, $[1 / (t_S + t_{CO})]$	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z External Switching Characteristics (Cont.)**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MG}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-2.5	-2.7	-3	-3.5	Units
In/Out Delays						
t_{IN}	Input Buffer Delay	—	0.60	—	0.60	—
t_{GOE}	Global OE Pin Delay	—	2.04	—	2.54	—
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	0.78	—	1.28	—
t_{BUF}	Delay through Output Buffer	—	0.85	—	0.85	—
t_{EN}	Output Enable Time	—	0.96	—	0.96	—
t_{DIS}	Output Disable Time	—	0.96	—	0.96	—
Routing/GLB Delays						
t_{ROUTE}	Delay through GRP	—	0.61	—	0.81	—
t_{MCELL}	Macrocell Delay	—	0.45	—	0.55	—
t_{INREG}	Input Buffer to Macrocell Register Delay	—	0.11	—	0.31	—
t_{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—
t_{PDb}	5-PT Bypass Propagation Delay	—	0.44	—	0.44	—
t_{PDi}	Macrocell Propagation Delay	—	0.64	—	0.64	—
Register/Latch Delays						
t_S	D-Register Setup Time (Global Clock)	0.92	—	1.12	—	1.02
t_{S_PT}	D-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
t_{ST}	T-Register Setup Time (Global Clock)	1.12	—	1.32	—	1.22
t_{ST_PT}	T-Register Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
t_H	D-Register Hold Time	0.88	—	0.68	—	0.98
t_{HT}	T-Register Hold Time	0.88	—	0.68	—	0.98
t_{SIR}	D-Input Register Setup Time (Global Clock)	0.82	—	1.37	—	1.27
t_{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45
t_{HIR}	D-Input Register Hold Time (Global Clock)	0.88	—	0.63	—	0.73
t_{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	0.63	—	0.73
t_{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.52	—
t_{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25
t_{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88
t_{SL}	Latch Setup Time (Global Clock)	0.92	—	1.12	—	1.02
t_{SL_PT}	Latch Setup Time (Product Term Clock)	1.42	—	1.32	—	1.32
t_{HL}	Latch Hold Time	1.17	—	1.17	—	1.17
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—

ispMACH 4000Z Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t_{IN}	Input Buffer Delay	—	0.75	—	0.80	—	0.75	ns
t_{GOE}	Global OE Pin Delay	—	2.25	—	2.25	—	2.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	1.60	—	1.60	—	1.95	ns
t_{BUF}	Delay through Output Buffer	—	0.75	—	0.90	—	0.90	ns
t_{EN}	Output Enable Time	—	2.25	—	2.25	—	2.50	ns
t_{DIS}	Output Disable Time	—	1.35	—	1.35	—	2.50	ns
Routing/GLB Delays								
t_{ROUTE}	Delay through GRP	—	1.60	—	1.60	—	2.15	ns
t_{MCELL}	Macrocell Delay	—	0.65	—	0.75	—	0.85	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	0.91	—	1.00	—	1.00	ns
t_{FBK}	Internal Feedback Delay	—	0.05	—	0.00	—	0.00	ns
t_{PDb}	5-PT Bypass Propagation Delay	—	0.40	—	0.40	—	0.40	ns
t_{PDi}	Macrocell Propagation Delay	—	0.25	—	0.25	—	0.65	ns
Register/Latch Delays								
t_S	D-Register Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t_{S_PT}	D-Register Setup Time (Product Term Clock)	1.35	—	1.95	—	1.90	—	ns
t_{ST}	T-Register Setup Time (Global Clock)	1.00	—	1.15	—	1.10	—	ns
t_{ST_PT}	T-register Setup Time (Product Term Clock)	1.55	—	1.75	—	2.10	—	ns
t_H	D-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
t_{HT}	T-Resister Hold Time	1.40	—	1.55	—	1.80	—	ns
t_{SIR}	D-Input Register Setup Time (Global Clock)	0.94	—	0.90	—	1.50	—	ns
t_{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t_{HIR}	D-Input Register Hold Time (Global Clock)	1.06	—	1.20	—	1.10	—	ns
t_{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	1.00	—	1.00	—	ns
t_{COi}	Register Clock to Output/Feedback MUX Time	—	0.65	—	0.70	—	0.65	ns
t_{CES}	Clock Enable Setup Time	1.00	—	2.00	—	2.00	—	ns
t_{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t_{SL}	Latch Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t_{SL_PT}	Latch Setup Time (Product Term Clock)	1.55	—	1.95	—	1.90	—	ns
t_{HL}	Latch Hold Time	1.40	—	1.80	—	1.80	—	ns
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.40	—	0.33	—	0.33	ns
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.30	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.28	—	0.28	—	1.27	ns
t_{SRR}	Asynchronous Reset or Set Recovery Delay	—	2.00	—	1.67	—	1.80	ns
Control Delays								
t_{BCLK}	GLB PT Clock Delay	—	1.30	—	1.50	—	1.55	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	1.50	—	1.70	—	1.55	ns
t_{BSR}	GLB PT Set/Reset Delay	—	1.10	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.22	—	2.02	—	1.83	ns

ispMACH 4000V/B/C Timing Adders¹

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders											
t_{INDIO}	t_{INREG}	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
t_{EXP}	t_{MCELL}	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
t_{ORP}	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
t_{BLA}	t_{ROUTE}	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters											
LVTTL_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	t_{IN} , t_{GCLK_IN} , t_{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters											
LVTTL_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	t_{BUF} , t_{EN} , t_{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t_{BUF} , t_{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

Signal Descriptions

Signal Names		Description
TMS		Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK		Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI		Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO		Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO		These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND		Ground
NC		Not Connected
V _{CC}		The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I		These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}		The power supply pins for each I/O bank.
yzz		Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
		ispMACH 4032
		ispMACH 4064
		ispMACH 4128
		ispMACH 4256
		ispMACH 4384
		ispMACH 4512

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C									
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208								
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16								
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵								
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB		8 I/Os / GLB		12 I/Os / GLB		4 I/Os / GLB		8 I/Os / GLB		10 I/Os / GLB		8 I/Os / GLB		8 I/Os / GLB		8 I/Os / GLB		4 I/Os / GLB	

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z		4064Z			4128Z			4256Z									
Number of I/Os	32	32	64			64	96	64	96 ¹	128								
Number of GLBs	2	4	4			8	8	16	16	16								
Number of I/Os / GLB	16	8	16			8	12	4	8	8								
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB		8 I/Os / GLB		12 I/Os / GLB		4 I/Os / GLB		8 I/Os / GLB		8 I/Os / GLB		8 I/Os / GLB	

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.

2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.

3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
42	0	A2	A^2	A4	A^2
43	0	A3	A^3	A6	A^3
44	0	A4	A^4	A8	A^4

**ispMACH 4032V/B/C/Z and 4064V/B/C/Z Logic Signal Connections:
48-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C/Z		ispMACH 4064V/B/C		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5	A8	A^5
3	0	A6	A^6	A12	A^6	A10	A^6
4	0	A7	A^7	A14	A^7	A11	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0	B15	B^7
8	0	A9	A^9	B2	B^1	B12	B^6
9	0	A10	A^10	B4	B^2	B10	B^5
10	0	A11	A^11	B6	B^3	B8	B^4
11	-	TCK	-	TCK	-	TCK	-
12	-	VCC	-	VCC	-	VCC	-
13	-	GND	-	GND	-	GND	-
14	0	A12	A^12	B8	B^4	B6	B^3
15	0	A13	A^13	B10	B^5	B4	B^2
16	0	A14	A^14	B12	B^6	B2	B^1
17	0	A15	A^15	B14	B^7	B0	B^0
18	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
19	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
20	1	B0	B^0	C0	C^0	C0	C^0
21	1	B1	B^1	C2	C^1	C1	C^1
22	1	B2	B^2	C4	C^2	C2	C^2
23	1	B3	B^3	C6	C^3	C4	C^3
24	1	B4	B^4	C8	C^4	C6	C^4
25	-	TMS	-	TMS	-	TMS	-
26	1	B5	B^5	C10	C^5	C8	C^5
27	1	B6	B^6	C12	C^6	C10	C^6
28	1	B7	B^7	C14	C^7	C11	C^7
29	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
30	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
31	1	B8	B^8	D0	D^0	D15	D^7
32	1	B9	B^9	D2	D^1	D12	D^6

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
19	0	C13	C^10
20	0	C12	C^9
21	0	C10	C^8
22	0	C9	C^7
23	0	C8	C^6
24	0	GND (Bank 0)	-
25	0	C6	C^5
26	0	C5	C^4
27	0	C4	C^3
28	0	C2	C^2
29	0	C0	C^0
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D^11
35	0	D13	D^10
36	0	D12	D^9
37	0	D10	D^8
38	0	D9	D^7
39	0	D8	D^6
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D^5
43	0	D5	D^4
44	0	D4	D^3
45	0	D2	D^2
46	0	D1	D^1
47	0	D0	D^0
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E^0
53	1	E1	E^1
54	1	E2	E^2
55	1	E4	E^3
56	1	E5	E^4
57	1	E6	E^5
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E^6
61	1	E9	E^7

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
105	1	VCCO (Bank 1)	-
106	1	H6	H^5
107	1	H5	H^4
108	1	H4	H^3
109	1	H2	H^2
110	1	H1	H^1
111	1	H0/GOE1	H^0
112	1	CLK3/I	-
113	0	GND (Bank 0)	-
114	0	CLK0/I	-
115	0	VCC	-
116	0	A0/GOE0	A^0
117	0	A1	A^1
118	0	A2	A^2
119	0	A4	A^3
120	0	A5	A^4
121	0	A6	A^5
122	0	VCCO (Bank 0)	-
123	0	GND (Bank 0)	-
124	0	A8	A^6
125	0	A9	A^7
126	0	A10	A^8
127	0	A12	A^9
128	0	A14	A^11

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	GND	-	GND	-	GND	-
B2	-	TDI	-	TDI	-	TDI	-
C1	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
C3	0	NC	-	B0	B^0	C12	C^6
C2	0	A8	A^8	B1	B^1	C10	C^5
D1	0	A9	A^9	B2	B^2	C8	C^4
D3	0	A10	A^10	B4	B^3	C6	C^3
D2	0	A11	A^11	B5	B^4	C4	C^2
E1	0	NC	-	B6	B^5	C2	C^1
E2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-
2	-	TDI	-	TDI	-
3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
4	0	B0	B^0	C12	C^6
5	0	B1	B^1	C10	C^5
6	0	B2	B^2	C8	C^4
7	0	B4	B^3	C6	C^3
8	0	B5	B^4	C4	C^2
9	0	B6	B^5	C2	C^1
10	0	GND (Bank 0)	-	GND (Bank 0)	-
11	0	B8	B^6	D14	D^7
12	0	B9	B^7	D12	D^6
13	0	B10	B^8	D10	D^5
14	0	B12	B^9	D8	D^4
15	0	B13	B^10	D6	D^3
16	0	B14	B^11	D4	D^2
17	-	NC ²	-	I ²	-
18	0	GND (Bank 0) ¹	-	NC ¹	-
19	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
20	0	NC ²	-	I ²	-
21	0	C14	C^11	E2	E^1
22	0	C13	C^10	E4	E^2
23	0	C12	C^9	E6	E^3
24	0	C10	C^8	E8	E^4
25	0	C9	C^7	E10	E^5
26	0	C8	C^6	E12	E^6
27	0	GND (Bank 0)	-	GND (Bank 0)	-
28	0	C6	C^5	F2	F^1
29	0	C5	C^4	F4	F^2
30	0	C4	C^3	F6	F^3
31	0	C2	C^2	F8	F^4
32	0	C1	C^1	F10	F^5
33	0	C0	C^0	F12	F^6
34	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
35	-	TCK	-	TCK	-
36	-	VCC	-	VCC	-
37	-	GND	-	GND	-
38	0	NC ²	-	I ²	-
39	0	D14	D^11	G12	G^6
40	0	D13	D^10	G10	G^5
41	0	D12	D^9	G8	G^4
42	0	D10	D^8	G6	G^3

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
60	0	H8	H^4	L8	L^4	P8	P^4
61	0	H6	H^3	L6	L^3	P6	P^3
62	0	H4	H^2	L4	L^2	P4	P^2
63	0	H2	H^1	L2	L^1	P2	P^1
64	0	H0	H^0	L0	L^0	P0	P^0
65	-	GND	-	GND	-	GND	-
66	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
67	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
68	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
69	-	VCC	-	VCC	-	VCC	-
70	1	I0	I^0	M0	M^0	AX0	AX^0
71	1	I2	I^1	M2	M^1	AX2	AX^1
72	1	I4	I^2	M4	M^2	AX4	AX^2
73	1	I6	I^3	M6	M^3	AX6	AX^3
74	1	I8	I^4	M8	M^4	AX8	AX^4
75	1	I10	I^5	M10	M^5	AX10	AX^5
76	1	I12	I^6	M12	M^6	AX12	AX^6
77	1	I14	I^7	M14	M^7	AX14	AX^7
78	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
79	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
80	1	J0	J^0	N0	N^0	BX0	BX^0
81	1	J2	J^1	N2	N^1	BX2	BX^1
82	1	J4	J^2	N4	N^2	BX4	BX^2
83	1	J6	J^3	N6	N^3	BX6	BX^3
84	1	J8	J^4	N8	N^4	BX8	BX^4
85	1	J10	J^5	N10	N^5	BX10	BX^5
86	1	J12	J^6	N12	N^6	BX12	BX^6
87	1	J14	J^7	N14	N^7	BX14	BX^7
88	-	VCC	-	VCC	-	VCC	-
89	-	NC	-	NC	-	NC	-
90	-	GND	-	GND	-	GND	-
91	-	TMS	-	TMS	-	TMS	-
92	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
93	1	K14	K^7	O14	O^7	CX14	CX^7
94	1	K12	K^6	O12	O^6	CX12	CX^6
95	1	K10	K^5	O10	O^5	CX10	CX^5
96	1	K8	K^4	O8	O^4	CX8	CX^4
97	1	K6	K^3	O6	O^3	CX6	CX^3
98	1	K4	K^2	O4	O^2	CX4	CX^2
99	1	K2	K^1	O2	O^1	CX2	CX^1
100	1	K0	K^0	O0	O^0	CX0	CX^0

ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5M132I	64	1.8	5	csBGA	132	64	I
	LC4064ZC-75M132I	64	1.8	7.5	csBGA	132	64	I
	LC4064ZC-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064ZC-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064ZC-5M56I	64	1.8	5	csBGA	56	34	I
	LC4064ZC-75M56I	64	1.8	7.5	csBGA	56	34	I
	LC4064ZC-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064ZC-75T48I	64	1.8	7.5	TQFP	48	32	I
LC4128ZC	LC4128ZC-75M132I	128	1.8	7.5	csBGA	132	96	I
	LC4128ZC-75T100I	128	1.8	7.5	TQFP	100	64	I
LC4256ZC	LC4256ZC-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256ZC-75M132I	256	1.8	7.5	csBGA	132	96	I
	LC4256ZC-75T100I	256	1.8	7.5	TQFP	100	64	I

ispMACH 4000ZC (1.8V, Zero Power) Extended Temperature Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75T48E	32	1.8	7.5	TQFP	48	32	E
LC4064ZC	LC4064ZC-75T100E	64	1.8	7.5	TQFP	100	64	E
	LC4064ZC-75T48E	64	1.8	7.5	TQFP	48	32	E
LC4128ZC	LC4128ZC-75T100E	128	1.8	7.5	TQFP	100	64	E
LC4256ZC	LC4256ZC-75T176E	256	1.8	7.5	TQFP	176	128	E
	LC4256ZC-75T100E	256	1.8	7.5	TQFP	100	64	E

ispMACH 4000C (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25T48C	32	1.8	2.5	TQFP	48	32	C
	LC4032C-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032C-75T48C	32	1.8	7.5	TQFP	48	32	C
	LC4032C-25T44C	32	1.8	2.5	TQFP	44	30	C
	LC4032C-5T44C	32	1.8	5	TQFP	44	30	C
	LC4032C-75T44C	32	1.8	7.5	TQFP	44	30	C
LC4064C	LC4064C-25T100C	64	1.8	2.5	TQFP	100	64	C
	LC4064C-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064C-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064C-25T48C	64	1.8	2.5	TQFP	48	32	C
	LC4064C-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064C-75T48C	64	1.8	7.5	TQFP	48	32	C
	LC4064C-25T44C	64	1.8	2.5	TQFP	44	30	C
	LC4064C-5T44C	64	1.8	5	TQFP	44	30	C
	LC4064C-75T44C	64	1.8	7.5	TQFP	44	30	C

ispMACH 4000C (1.8V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032C-75T48I	32	1.8	7.5	TQFP	48	32	I
	LC4032C-10T48I	32	1.8	10	TQFP	48	32	I
	LC4032C-5T44I	32	1.8	5	TQFP	44	30	I
	LC4032C-75T44I	32	1.8	7.5	TQFP	44	30	I
	LC4032C-10T44I	32	1.8	10	TQFP	44	30	I
LC4064C	LC4064C-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064C-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064C-10T100I	64	1.8	10	TQFP	100	64	I
	LC4064C-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064C-75T48I	64	1.8	7.5	TQFP	48	32	I
	LC4064C-10T48I	64	1.8	10	TQFP	48	32	I
	LC4064C-5T44I	64	1.8	5	TQFP	44	30	I
	LC4064C-75T44I	64	1.8	7.5	TQFP	44	30	I
	LC4064C-10T44I	64	1.8	10	TQFP	44	30	I
LC4128C	LC4128C-5T128I	128	1.8	5	TQFP	128	92	I
	LC4128C-75T128I	128	1.8	7.5	TQFP	128	92	I
	LC4128C-10T128I	128	1.8	10	TQFP	128	92	I
	LC4128C-5T100I	128	1.8	5	TQFP	100	64	I
	LC4128C-75T100I	128	1.8	7.5	TQFP	100	64	I
	LC4128C-10T100I	128	1.8	10	TQFP	100	64	I
LC4256C	LC4256C-5FT256AI	256	1.8	5	ftBGA	256	128	I
	LC4256C-75FT256AI	256	1.8	7.5	ftBGA	256	128	I
	LC4256C-10FT256AI	256	1.8	10	ftBGA	256	128	I
	LC4256C-5FT256BI	256	1.8	5	ftBGA	256	160	I
	LC4256C-75FT256BI	256	1.8	7.5	ftBGA	256	160	I
	LC4256C-10FT256BI	256	1.8	10	ftBGA	256	160	I
	LC4256C-5F256AI ¹	256	1.8	5	fpBGA	256	128	I
	LC4256C-75F256AI ¹	256	1.8	7.5	fpBGA	256	128	I
	LC4256C-10F256AI ¹	256	1.8	10	fpBGA	256	128	I
	LC4256C-5F256BI ¹	256	1.8	5	fpBGA	256	160	I
	LC4256C-75F256BI ¹	256	1.8	7.5	fpBGA	256	160	I
	LC4256C-10F256BI ¹	256	1.8	10	fpBGA	256	160	I
	LC4256C-5T176I	256	1.8	5	TQFP	176	128	I
	LC4256C-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256C-10T176I	256	1.8	10	TQFP	176	128	I
	LC4256C-5T100I	256	1.8	5	TQFP	100	64	I
	LC4256C-75T100I	256	1.8	7.5	TQFP	100	64	I
	LC4256C-10T100I	256	1.8	10	TQFP	100	64	I

ispMACH 4000C (1.8V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384C	LC4384C-5FT256I	384	1.8	5	ftBGA	256	192	I
	LC4384C-75FT256I	384	1.8	7.5	ftBGA	256	192	I
	LC4384C-10FT256I	384	1.8	10	ftBGA	256	192	I
	LC4384C-5F256I ¹	384	1.8	5	fpBGA	256	192	I
	LC4384C-75F256I ¹	384	1.8	7.5	fpBGA	256	192	I
	LC4384C-10F256I ¹	384	1.8	10	fpBGA	256	192	I
	LC4384C-5T176I	384	1.8	5	TQFP	176	128	I
	LC4384C-75T176I	384	1.8	7.5	TQFP	176	128	I
	LC4384C-10T176I	384	1.8	10	TQFP	176	128	I
LC4512C	LC4512C-5FT256I	512	1.8	5	ftBGA	256	208	I
	LC4512C-75FT256I	512	1.8	7.5	ftBGA	256	208	I
	LC4512C-10FT256I	512	1.8	10	ftBGA	256	208	I
	LC4512C-5F256I ¹	512	1.8	5	fpBGA	256	208	I
	LC4512C-75F256I ¹	512	1.8	7.5	fpBGA	256	208	I
	LC4512C-10F256I ¹	512	1.8	10	fpBGA	256	208	I
	LC4512C-5T176I	512	1.8	5	TQFP	176	128	I
	LC4512C-75T176I	512	1.8	7.5	TQFP	176	128	I
	LC4512C-10T176I	512	1.8	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25T48C	32	2.5	2.5	TQFP	48	32	C
	LC4032B-5T48C	32	2.5	5	TQFP	48	32	C
	LC4032B-75T48C	32	2.5	7.5	TQFP	48	32	C
	LC4032B-25T44C	32	2.5	2.5	TQFP	44	30	C
	LC4032B-5T44C	32	2.5	5	TQFP	44	30	C
	LC4032B-75T44C	32	2.5	7.5	TQFP	44	30	C
LC4064B	LC4064B-25T100C	64	2.5	2.5	TQFP	100	64	C
	LC4064B-5T100C	64	2.5	5	TQFP	100	64	C
	LC4064B-75T100C	64	2.5	7.5	TQFP	100	64	C
	LC4064B-25T48C	64	2.5	2.5	TQFP	48	32	C
	LC4064B-5T48C	64	2.5	5	TQFP	48	32	C
	LC4064B-75T48C	64	2.5	7.5	TQFP	48	32	C
	LC4064B-25T44C	64	2.5	2.5	TQFP	44	30	C
	LC4064B-5T44C	64	2.5	5	TQFP	44	30	C
LC4128B	LC4128B-27T128C	128	2.5	2.7	TQFP	128	92	C
	LC4128B-5T128C	128	2.5	5	TQFP	128	92	C
	LC4128B-75T128C	128	2.5	7.5	TQFP	128	92	C
	LC4128B-27T100C	128	2.5	2.7	TQFP	100	64	C
	LC4128B-5T100C	128	2.5	5	TQFP	100	64	C
	LC4128B-75T100C	128	2.5	7.5	TQFP	100	64	C

Lead-Free Packaging**ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Commercial Devices**

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35MN56C	32	1.8	3.5	Lead-free csBGA	56	32	C
	LC4032ZC-5MN56C	32	1.8	5	Lead-free csBGA	56	32	C
	LC4032ZC-75MN56C	32	1.8	7.5	Lead-free csBGA	56	32	C
	LC4032ZC-35TN48C	32	1.8	3.5	Lead-free TQFP	48	32	C
	LC4032ZC-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032ZC-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
LC4064ZC	LC4064ZC-37MN132C	64	1.8	3.7	Lead-free csBGA	132	64	C
	LC4064ZC-5MN132C	64	1.8	5	Lead-free csBGA	132	64	C
	LC4064ZC-75MN132C	64	1.8	7.5	Lead-free csBGA	132	64	C
	LC4064ZC-37TN100C	64	1.8	3.7	Lead-free TQFP	100	64	C
	LC4064ZC-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064ZC-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064ZC-37MN56C	64	1.8	3.7	Lead-free csBGA	56	32	C
	LC4064ZC-5MN56C	64	1.8	5	Lead-free csBGA	56	32	C
	LC4064ZC-75MN56C	64	1.8	7.5	Lead-free csBGA	56	32	C
	LC4064ZC-37TN48C	64	1.8	3.7	Lead-free TQFP	48	32	C
	LC4064ZC-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064ZC-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
LC4128ZC	LC4128ZC-42MN132C	128	1.8	4.2	Lead-free csBGA	132	96	C
	LC4128ZC-75MN132C	128	1.8	7.5	Lead-free csBGA	132	96	C
	LC4128ZC-42TN100C	128	1.8	4.2	Lead-free TQFP	100	64	C
	LC4128ZC-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256ZC	LC4256ZC-45TN176C	256	1.8	4.5	Lead-free TQFP	176	128	C
	LC4256ZC-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256ZC-45MN132C	256	1.8	4.5	Lead-free csBGA	132	96	C
	LC4256ZC-75MN132C	256	1.8	7.5	Lead-free csBGA	132	96	C
	LC4256ZC-45TN100C	256	1.8	4.5	Lead-free TQFP	100	64	C
	LC4256ZC-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5MN56I	32	1.8	5	Lead-free csBGA	56	32	I
	LC4032ZC-75MN56I	32	1.8	7.5	Lead-free csBGA	56	32	I
	LC4032ZC-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032ZC-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5MN132I	64	1.8	5	Lead-free csBGA	132	64	I
	LC4064ZC-75MN132I	64	1.8	7.5	Lead-free csBGA	132	64	I
	LC4064ZC-5TN100I	64	1.8	5	Lead-free TQFP	100	64	I
	LC4064ZC-75TN100I	64	1.8	7.5	Lead-free TQFP	100	64	I
	LC4064ZC-5MN56I	64	1.8	5	Lead-free csBGA	56	32	I
	LC4064ZC-75MN56I	64	1.8	7.5	Lead-free csBGA	56	32	I
	LC4064ZC-5TN48I	64	1.8	5	Lead-free TQFP	48	32	I
	LC4064ZC-75TN48I	64	1.8	7.5	Lead-free TQFP	48	32	I
LC4128ZC	LC4128ZC-75MN132I	128	1.8	7.5	Lead-free csBGA	132	96	I
	LC4128ZC-75TN100I	128	1.8	7.5	Lead-free TQFP	100	64	I
LC4256ZC	LC4256ZC-75TN176I	256	1.8	7.5	Lead-free TQFP	176	128	I
	LC4256ZC-75MN132I	256	1.8	7.5	Lead-free csBGA	132	96	I
	LC4256ZC-75TN100I	256	1.8	7.5	Lead-free TQFP	100	64	I

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75TN48E	32	1.8	7.5	Lead-free TQFP	48	32	E
LC4064ZC	LC4064ZC-75TN100E	64	1.8	7.5	Lead-free TQFP	100	64	E
	LC4064ZC-75TN48E	64	1.8	7.5	Lead-free TQFP	48	32	E
LC4128ZC	LC4128ZC-75TN100E	128	1.8	7.5	Lead-free TQFP	100	64	E
LC4256ZC	LC4256ZC-75TN176E	256	1.8	7.5	Lead-free TQFP	176	128	E
	LC4256ZC-75TN100E	256	1.8	7.5	Lead-free TQFP	100	64	E

ispMACH 4000C (1.8V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25TN48C	32	1.8	2.5	Lead-free TQFP	48	32	C
	LC4032C-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032C-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
	LC4032C-25TN44C	32	1.8	2.5	Lead-free TQFP	44	30	C
	LC4032C-5TN44C	32	1.8	5	Lead-free TQFP	44	30	C
	LC4032C-75TN44C	32	1.8	7.5	Lead-free TQFP	44	30	C